

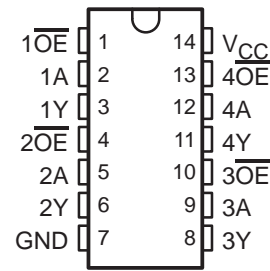
# SN74LVT125

## 3.3-V ABT QUADRUPLE BUS BUFFER WITH 3-STATE OUTPUTS

SCBS133F – MAY 1992 – REVISED OCTOBER 2003

- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V  $V_{CC}$ )
- Supports Unregulated Battery Operation Down to 2.7 V
- Typical  $V_{OLP}$  (Output Ground Bounce)  $<0.8$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

D, DB, NS, OR PW PACKAGE  
(TOP VIEW)



### description/ordering information

This bus buffer is designed specifically for low-voltage (3.3-V)  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVT125 features independent line drivers with 3-state outputs. Each output is in the high-impedance state when the associated output-enable ( $\overline{OE}$ ) input is high.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

### ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOIC – D	Tube	SN74LVT125D	LVT125
		Tape and reel	SN74LVT125DR	
	SOP – NS	Tape and reel	SN74LVT125NSR	LVT125
	SSOP – DB	Tape and reel	SN74LVT125DBR	LX125
	TSSOP – PW	Tube	SN74LVT125PW	LX125
		Tape and reel	SN74LVT125PWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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# SN74LVT125

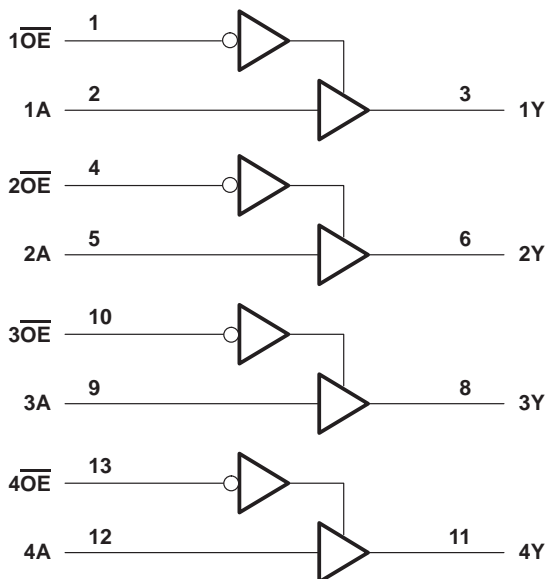
## 3.3-V ABT QUADRUPLE BUS BUFFER WITH 3-STATE OUTPUTS

SCBS133F – MAY 1992 – REVISED OCTOBER 2003

FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	-0.5 V to 4.6 V
Input voltage range, $V_I$ (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, $V_O$ (see Note 1)	-0.5 V to 7 V
Current into any output in the low state, $I_O$	128 mA
Current into any output in the high state, $I_{OH}$ (see Note 2)	64 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	-50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	-50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3):	
D package	86°C/W
DB package	96°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
 2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .  
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN74LVT125

## 3.3-V ABT QUADRUPLE BUS BUFFER WITH 3-STATE OUTPUTS

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### recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	2.7	3.6	V
$V_{IH}$	High-level input voltage	2		V
$V_{IL}$	Low-level input voltage		0.8	V
$V_I$	Input voltage		5.5	V
$I_{OH}$	High-level output current		-32	mA
$I_{OL}$	Low-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10 ns/V
$T_A$	Operating free-air temperature	-40	85	°C

NOTE 4: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
$V_{IK}$	$V_{CC} = 2.7$ V,	$I_I = -18$ mA			-1.2	V
$V_{OH}$	$V_{CC} = \text{MIN to MAX}^\ddagger$ ,	$I_{OH} = -100$ $\mu$ A	$V_{CC}-0.2$			V
	$V_{CC} = 2.7$ V,	$I_{OH} = -8$ mA	2.4			
	$V_{CC} = 3$ V	$I_{OH} = -32$ mA	2			
$V_{OL}$	$V_{CC} = 2.7$ V	$I_{OL} = 100$ $\mu$ A			0.2	V
		$I_{OL} = 24$ mA			0.5	
	$V_{CC} = 3$ V	$I_{OL} = 16$ mA			0.4	
		$I_{OL} = 32$ mA			0.5	
		$I_{OL} = 64$ mA			0.55	
$I_I$	$V_{CC} = 0$ or $\text{MAX}^\ddagger$ ,	$V_I = 5.5$ V			10	$\mu$ A
	$V_{CC} = 3.6$ V	$V_I = V_{CC}$ or GND	Control inputs		$\pm 1$	
		$V_I = V_{CC}$	Data inputs			
		$V_I = 0$			-5	
$I_{off}$	$V_{CC} = 0$ ,	$V_I$ or $V_O = 0$ to 4.5 V			$\pm 100$	$\mu$ A
$I_{I(\text{hold})}$	$V_{CC} = 3$ V	$V_I = 0.8$ V	Data inputs		75	$\mu$ A
		$V_I = 2$ V			-75	
$I_{OZH}$	$V_{CC} = 3.6$ V,	$V_O = 3$ V			5	$\mu$ A
$I_{OZL}$	$V_{CC} = 3.6$ V,	$V_O = 0.5$ V			-5	$\mu$ A
$I_{CC}$	$V_{CC} = 3.6$ V, $V_I = V_{CC}$ or GND	$I_O = 0$ ,	Outputs high	0.12	0.19	mA
			Outputs low	4.5	7	
			Outputs disabled	0.12	0.19	
$\Delta I_{CC}^\S$	$V_{CC} = 3$ V to 3.6 V,	One input at $V_{CC} - 0.6$ V,	Other inputs at $V_{CC}$ or GND		0.2	mA
$C_i$	$V_I = 3$ V or 0				4	pF
$C_o$	$V_O = 3$ V or 0				8	pF

† All typical values are at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$ .

‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.



**SN74LVT125**  
**3.3-V ABT QUADRUPLE BUS BUFFER**  
**WITH 3-STATE OUTPUTS**

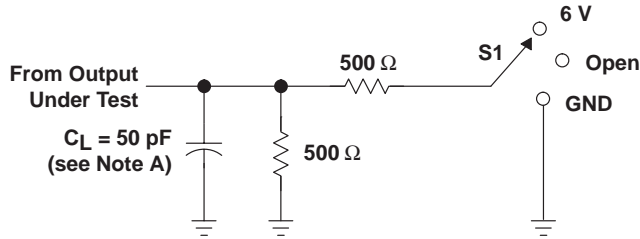
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switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$			$V_{CC} = 2.7\text{ V}$		UNIT
			MIN	TYP†	MAX	MIN	MAX	
$t_{PLH}$	A	Y	1	2.7	4	4.5		ns
$t_{PHL}$			1	2.9	3.9	4.9		
$t_{PZH}$	$\overline{OE}$	Y	1	3.4	4.7	6		ns
$t_{PZL}$			1.1	3.4	4.7	6.5		
$t_{PHZ}$	$\overline{OE}$	Y	1.8	3.7	5.1	5.7		ns
$t_{PLZ}$			1.3	2.6	4.5	4		

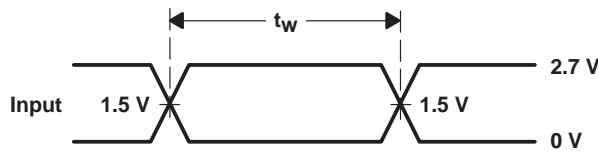
† All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

**PARAMETER MEASUREMENT INFORMATION**

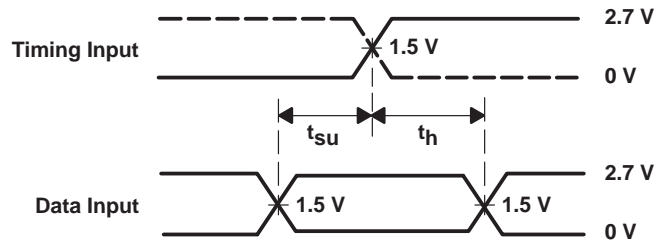


TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND

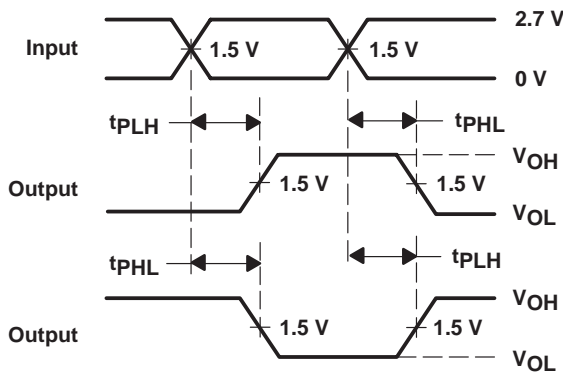
**LOAD CIRCUIT FOR OUTPUTS**



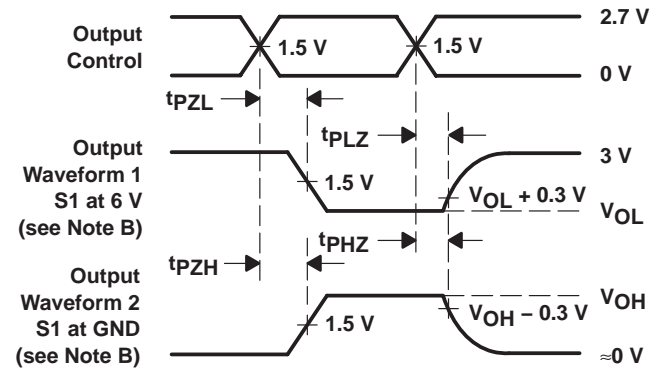
**VOLTAGE WAVEFORMS  
PULSE DURATION**



**VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.  
 D. The outputs are measured one at a time with one transition per measurement.  
 E. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVT125D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT125	<a href="#">Samples</a>
SN74LVT125DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LX125	<a href="#">Samples</a>
SN74LVT125DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT125	<a href="#">Samples</a>
SN74LVT125DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT125	<a href="#">Samples</a>
SN74LVT125NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT125	<a href="#">Samples</a>
SN74LVT125PW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LX125	<a href="#">Samples</a>
SN74LVT125PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LX125	<a href="#">Samples</a>
SN74LVT125PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LX125	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN74LVT125 :**

- Automotive : [SN74LVT125-Q1](#)
- Enhanced Product : [SN74LVT125-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT125DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LVT125DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVT125NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVT125PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVT125DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74LVT125DR	SOIC	D	14	2500	340.5	336.1	32.0
SN74LVT125NSR	SOP	NS	14	2000	356.0	356.0	35.0
SN74LVT125PWR	TSSOP	PW	14	2000	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LVT125D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LVT125D	D	SOIC	14	50	507	8	3940	4.32
SN74LVT125PW	PW	TSSOP	14	90	530	10.2	3600	3.5



# D0014A

# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

# DB0014A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



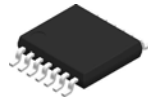
SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

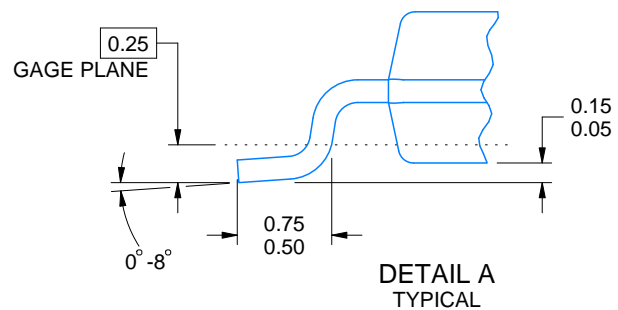
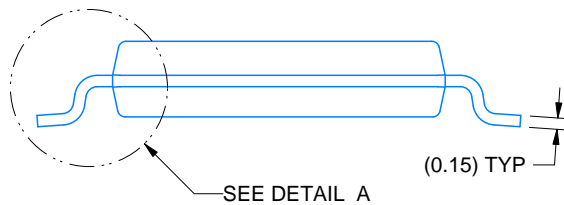
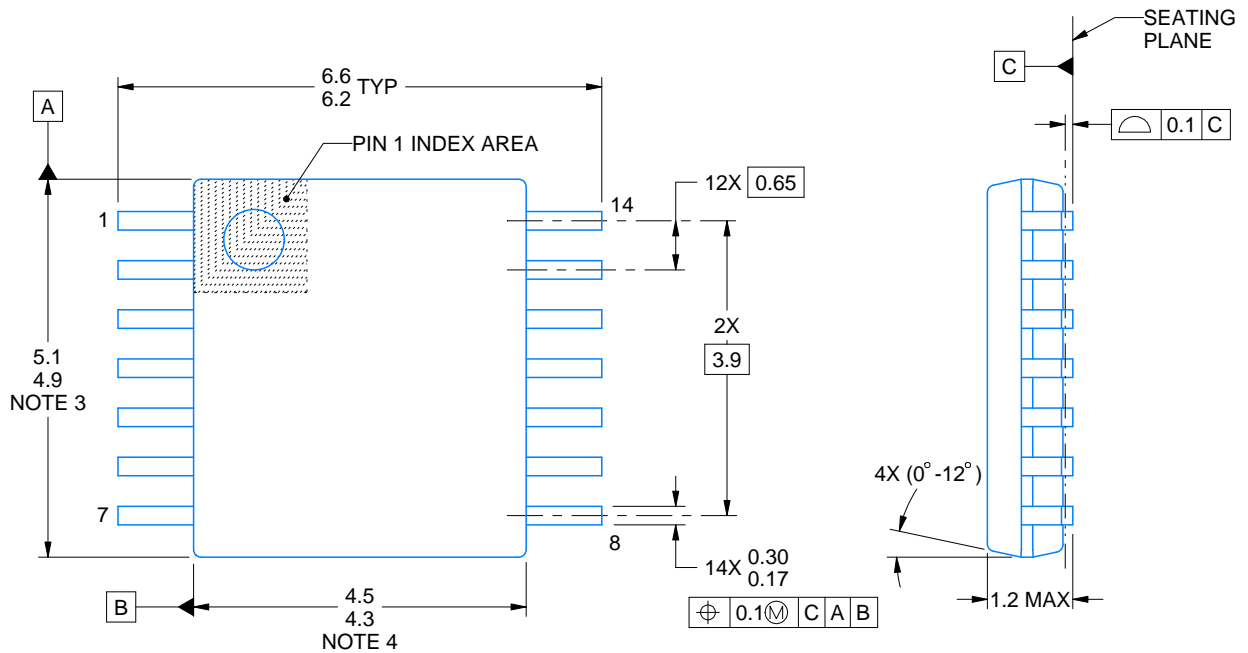
PW0014A



# PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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